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New Laser Solutions for Innovative Interconnects at ECTC in Las Vegas

Tualatin, OR, May 2016 — LPKF Laser & Electronics has announced it will exhibit at the 2016 Electronic Components and Technology Congerence (ECTC) which will be held June 1-2, 2016 at The Cosmopolitan in Las Vegas, NV.

LPKF, a leading manufacturer of laser systems for electronics manufacturing, will showcase its new solutions across the semiconductor packaging spectrum in booth 320.

One of the technologies highlighted by LPKF is the efficient via forming in large glass substrates (TGV); a process of creating through holes and blind vias, with defined diameters as small as 15 microns, using single-pulse glass modification through laser beam in combination with subsequent a standard wet etching process. Glass substrates with a thickness between 50 to 500 micron can be processed with this method. Clean-room compatibility and stress-free processing make this innovative laser-based process ideal for thin glass interposers and also for solid glass cores for FCBGA substrates – eliminating chips, burr, micro-cracks or voids.

LPKF has developed the new Vitrion laser system specifically developed for these applications. The system is designed for high volume mass production, capable of forming more than 5,000 homogeneous vias per second.

Another technology represented at the ECTC Conference will be Laser Direct Structuring (LDS-technology) for MEMS applications, a method of creating ultra-fine circuits directly on 3D parts used for chip packaging. The highly flexible and stress-free laser direct structuring process is designed for advanced electronic packaging where space is a premium and high layout-flexibility is much appreciated.

For more information on LPKF's semiconductor packaging technology solutions, visit LPKF in booth 320 at ECTC Technolgy Corner Exhibits or visit www.lpkf.com.

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About LPKF

Established in 1976, LPKF Laser & Electronics manufactures milling machines and laser systems used in circuit board and microelectronics fabrication, medical technology, the automotive sector, and the production of solar cells. LPKF's worldwide headquarters is located in Hannover, Germany and its North American headquarters resides near Portland, Ore.